

## ABSTRACT

While a vicinity of a bottom surface-side region of a pressure-sensitive adhesive sheet, corresponding to an adhesion region of a semiconductor chip, is sucked and held, a plurality of protruding portions of a removing member are brought into contact with the bottom surface of the semiconductor chip through the adhesive sheet at the adhesion region. Also, the adhesive sheet is sucked in between the respective protruding portions so as to change an adhesive surface bond of the semiconductor chip to the adhesive sheet to point bonding. Further, the removing member is moved along the bottom surface of the semiconductor chip so as to change the position of the point bonding and decrease the adhesive bonding force to the adhesive sheet. Then, the semiconductor chip is removed from the adhesive sheet.